

#### Nch 650V 4A Power MOSFET

V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	1.050Ω
I <sub>D</sub>	±4.0A
P <sub>D</sub>	58W

# Outline TO-252

#### Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

## •Inner circuit (1) Gate (2) Drain \*1 Body Diode

## Application

Switching

#### Packaging specifications

Packing	Embossed Tape
Packing code	TL1
Marking	R6504K
Quantity (pcs)	2500

## ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	650	V	
Continuous drain current (T <sub>c</sub> = 25°C)		I <sub>D</sub> *1	±4.0	Α
Pulsed drain current	I <sub>DP</sub> *2	±12	Α	
Static		V	±20	V
Gate - Source voltage	AC(f>1Hz)	$V_{GSS}$	±30	V
Avalanche current, single pulse		I <sub>AS</sub>	0.8	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	34.8	mJ
Power dissipation (T <sub>c</sub> = 25°C)		P <sub>D</sub>	58	W
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tempera	ature range	T <sub>stg</sub>	-55 to +150	°C

#### ●Thermal resistance

Downwortow	Cymah al	Values			1.1-:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	2.2	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol Conditions		Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage		$V_{GS} = 0V$ , $I_D = 1mA$	650	-	1	V	
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ	
		T <sub>j</sub> = 125°C	-	-	1000		
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 130 \mu A$	3	-	5	V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.5A					
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.955	1.050	Ω	
		T <sub>j</sub> = 125°C	-	2.02	-		
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	3.3	-	Ω	

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions		Unit			
Parameter	Symbol	mbol Conditions		Тур.	Max.	Uriil	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	270	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	270	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	15	-		
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	16	-		
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 2A	-	17	1	20	
Turn - off delay time	t <sub>d(off)</sub> *6	R <sub>L</sub> ~ 150Ω	_	30	-	ns	
Fall time	<b>t</b> <sub>f</sub> *6	$R_G = 10\Omega$	-	35	-		

### ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol Conditions -		Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Total gate charge	Q <sub>g</sub> *6	V <sub>DD</sub> ≃ 300V	-	10	-	
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 4A	-	2.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6	V <sub>GS</sub> = 10V	-	4.8	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300V$ , $I_D = 4A$	-	6.5	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on a epoxy PCB FR4 (20mm x 20mm x 0.8mm)

<sup>\*6</sup> Pulsed

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Source current	I <sub>S</sub> *1	- T <sub>C</sub> = 25°C	1	-	4.0	Α	
Pulsed source current	l <sub>SP</sub> *2	1C - 23 C	1	-	12	Α	
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V$ , $I_S = 4A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *6		-	290	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 4A di/dt = 100A/μs	-	1.9	-	μC	
Peak reverse recovery current	<sub>rr</sub> *6		-	13	-	Α	

Fig.1 Power Dissipation Derating Curve

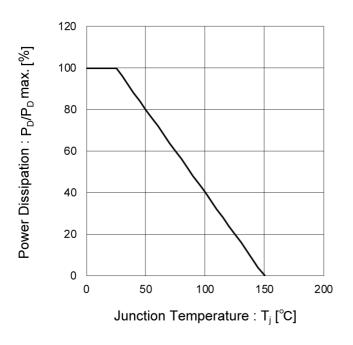


Fig.2 Drain Current Derating Curve

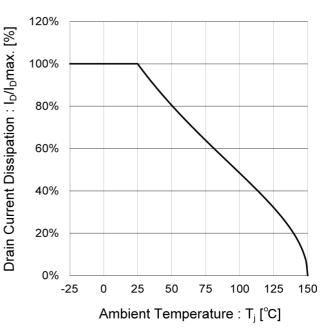


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

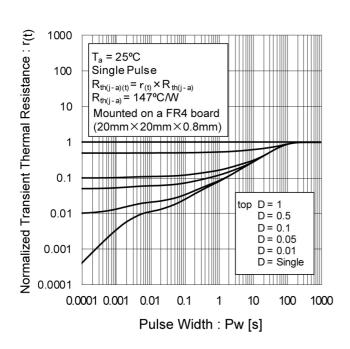
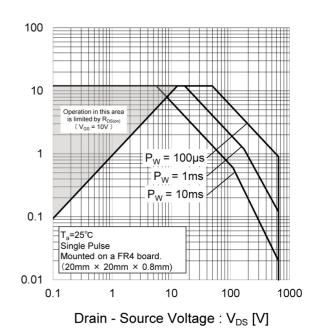


Fig.4 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Derating Curve

120 Avalanche Energy: EAS / EAS max [%] 100 80 60 40 20 0 0 25 50 75 100 125 175 Junction Temperature : T<sub>j</sub> [°C]

Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

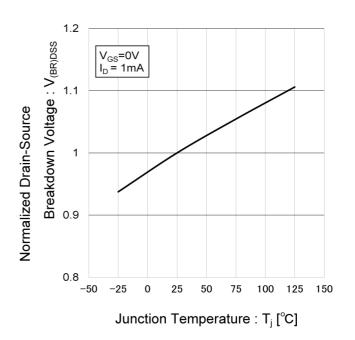


Fig.7 Typical Output Characteristics(I)

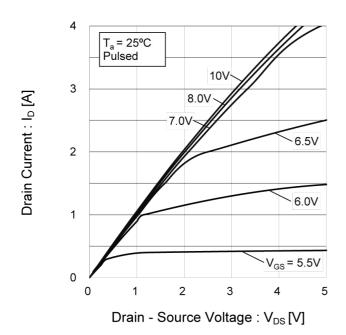
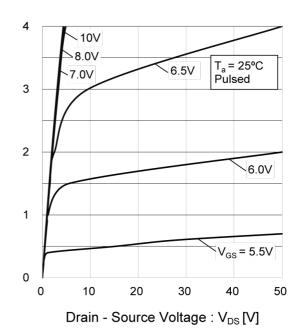


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

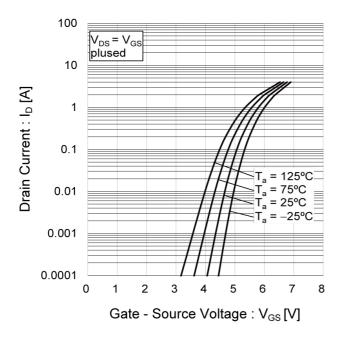


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

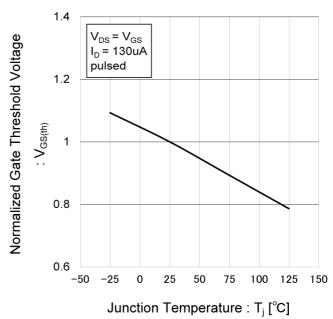


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

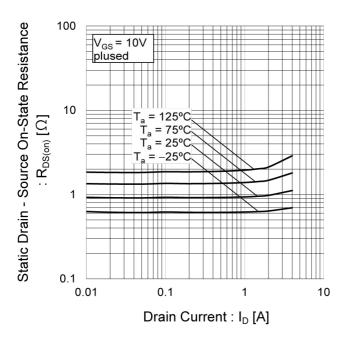


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

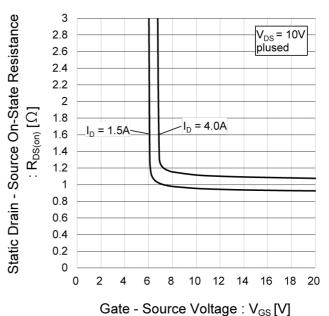


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

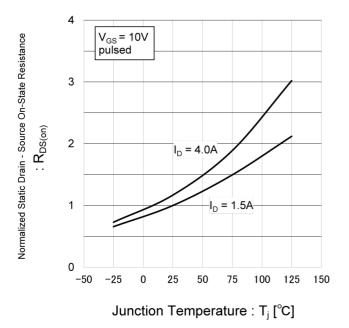
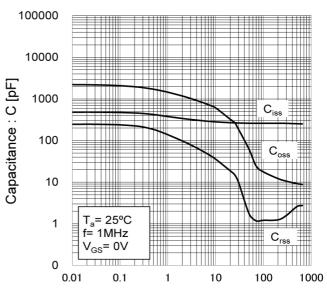


Fig.14 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.15 Switching Characteristics

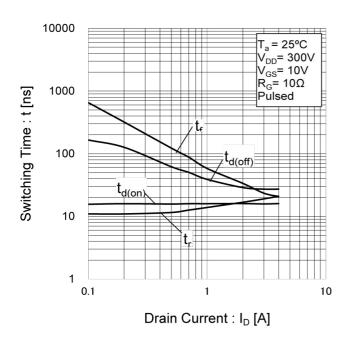
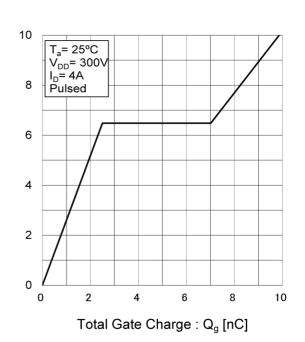


Fig.16 Typical Gate Charge



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

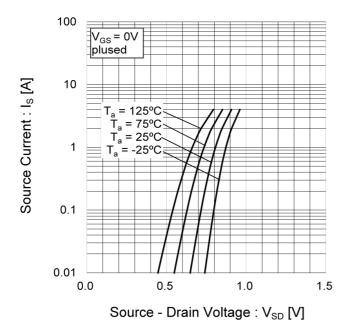
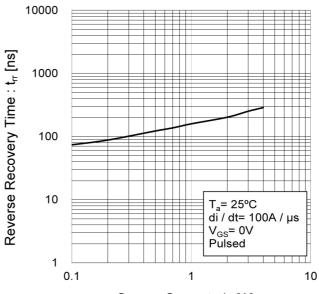


Fig.18 Reverse Recovery Time vs. Source Current



Source Current : I<sub>S</sub> [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

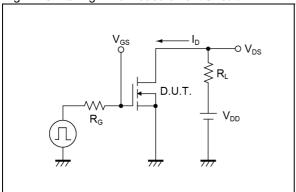


Fig.2-1 Gate Charge Measurement Circuit

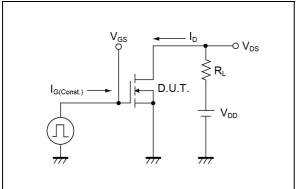


Fig.3-1 Avalanche Measurement Circuit

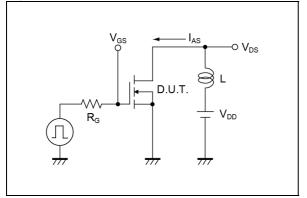


Fig.4-1 trr Measurement Circuit

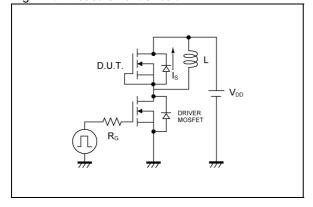


Fig.1-2 Switching Waveforms

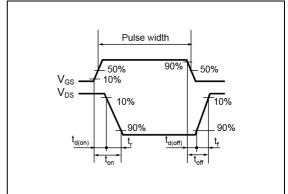


Fig.2-2 Gate Charge Waveform

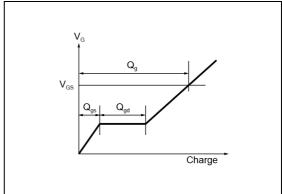


Fig.3-2 Avalanche Waveform

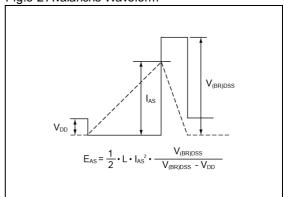
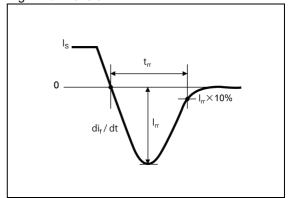
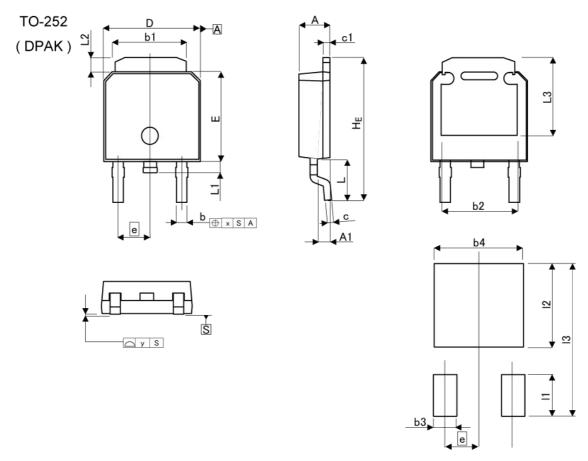


Fig.4-2 trr Waveform



#### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INCI	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	5.	35	0.2	11
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	70	0.1	06
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	:09
Х	1	0.25	-	0.010
У	-	0.10	-	0.004

5	MILIME	TERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
b3		1.15	2	0.045	
b4	(-)(	5.55	-	0.219	
11	2.0	2.77	2	0.109	
12	1-0	5.50	-	0.217	
13	-	10.40	2	0.409	

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSIII	CLASS II b	CL ACCIII
CLASSIV		CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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